PRODUCT SPECIFICATION

6.9” TFT LCD MODULE
MODEL: YDP LCD I 690 MI 001

ROHS

< ◇> Preliminary Specification

< ◆> Finally Specification

CUSTOMER’S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY
TFT S. G. H 20220919	———	———	TFT L. Q 20220919

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2022.09.19	LQ	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	6.9”	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally black	
Resolution	720 RGB x 1440	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	81.71(H) x 163.34 (V) x 2.35 (T) (Note1)	mm
Active Area	78.0192 (H) x 156.0384 (V)	mm
Pixel Size	108.36 (H) x 108.36 (V)	um
Pixel Arrangement	RGB Vertical Stripe	
Display Colors	16.7M	
Interface	4 Lane MIPI	
With or without touch panel	Without	
Driver IC	GC9702P	-
Operating Temperature	**-20～70**	ºC
Storage Temperature	**-30～80**	ºC
Weight	67	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25ºC

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDDA	-0.3	4.6	V
	VDDIO	-0.3	4.6	V
Storage temperature	T_{STG}	**-30**	**+80**	ºC
Operating temperature	T_{OP}	**-20**	**+70**	ºC

Note 1: If Ta below 50ºC, the maximal humidity is 90%RH, if Ta over 50ºC, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10℃, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item		Symbol	Min.	Typ.	Max.	Unit
Supply Voltage		VDDA	2.5	2.8	3.3	V
		VDDIO	1.65	1.8	3.3	V
Logic High level input voltage		V_{IH}	0.7*VDDIO	-	VDDIO	mV
Logic Low level input voltage		V_{IL}	-0.3	-	0.3*VDDIO	mV
Logic High level Output voltage		V_{OH}	0.8*VDDIO	-	VDDIO	mV
Logic Low level Output voltage		V_{OL}	0	-	0.2*VDDIO	mV
Current Consumption All white	Logic	I_{VDDA+} I_{VDDIO}	-	27	-	mA
	Analog					

5. Backlight Characteristic

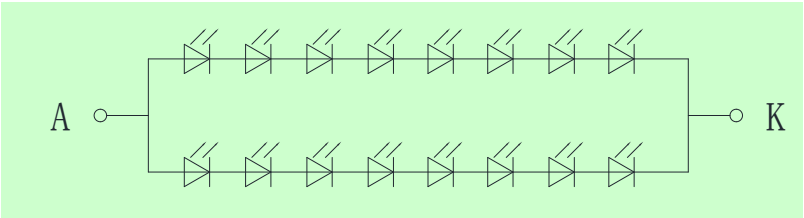
5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	Ta=25 ºC, I_F=20mA/LED	21.6	**24.0**	26.4	V
Forward Current	I_F	Ta=25 ºC, V_F=3.0V/LED	-	**40**	-	mA
Power dissipation	P_D		-	**960**	-	mW
Uniformity	Avg		-	80	-	%
LED working life(25℃)	-		-	30,000	-	Hrs
Drive method	Constant current					
LED Configuration	16 White LEDs (8 LEDs in one string and 2 groups in parallel)					

Note1：LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 ºC,60%RH±5%, I_F=20mA/LED.

5.2. Backlight Characteristic



6. Optical Characteristics

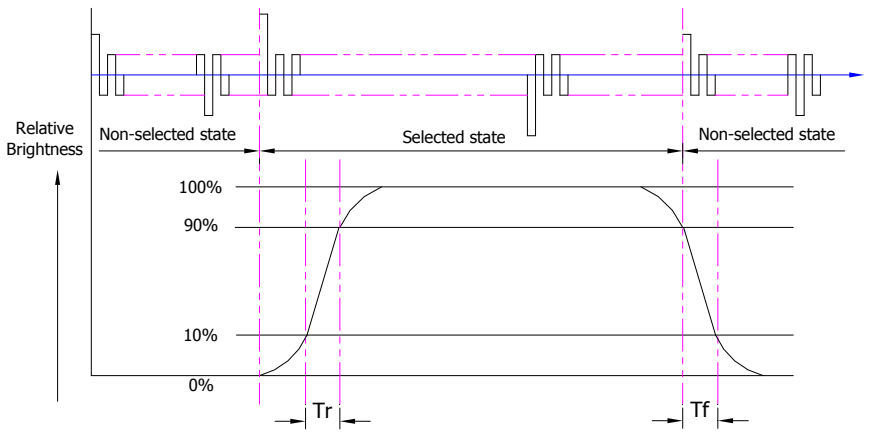
6.1. Optical Characteristics

Ta=25ºC, VDDA=2.8V

	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
Backlight On (Transmissive Mode)	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle θX = φY =0º	**192**	**240**	-	cd/m²
	Contrast ratio(See 6.3)		CR		1000	1200	-	
	Response time (See 6.2)		TR+TF		-	25	35	ms
	Chromaticity Transmissive (See 6.5)	Red	XR		0.617	**0.667**	0.717	
			YR		0.273	**0.323**	0.373	
		Green	XG		0.255	**0.305**	0.355	
			YG		0.589	**0.639**	0.689	
		Blue	XB		0.082	**0.132**	0.182	
			YB		0.030	**0.080**	0.130	
		White	XW		0.221	**0.271**	0.321	
			YW		0.274	**0.324**	0.374	
	Viewing Angle (See 6.4)	Horizontal	θX+	Center CR≥10	80	85	-	Deg.
			θX-		80	85	-	
		Vertical	φY+		80	85	-	
			φY-		80	85	-	
	NTSC Ratio(Gamut)				65	70	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

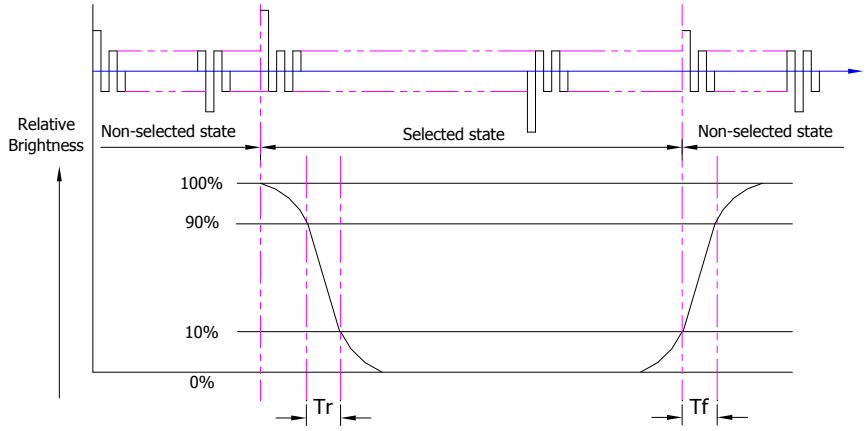


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

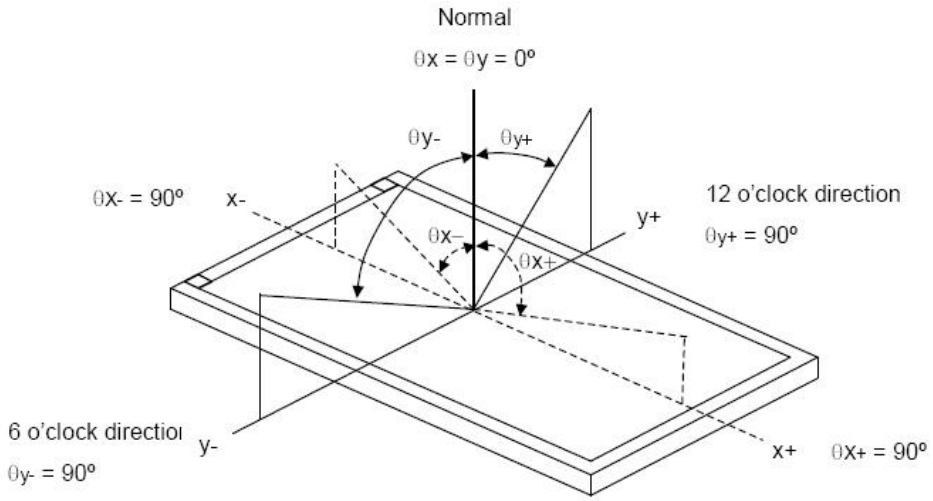
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



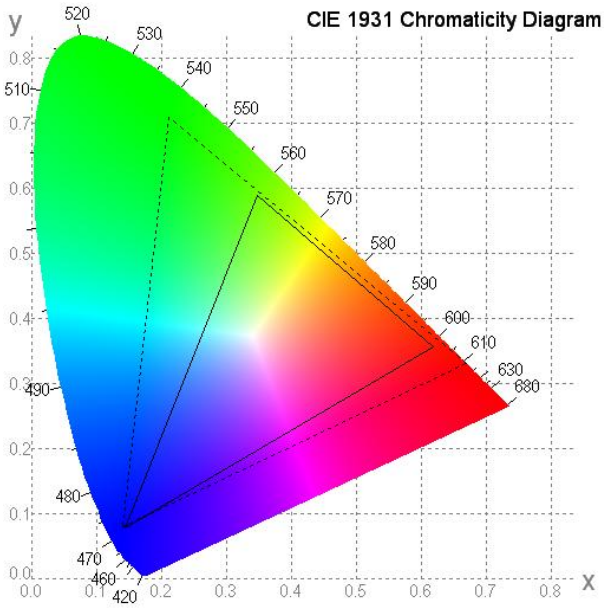
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

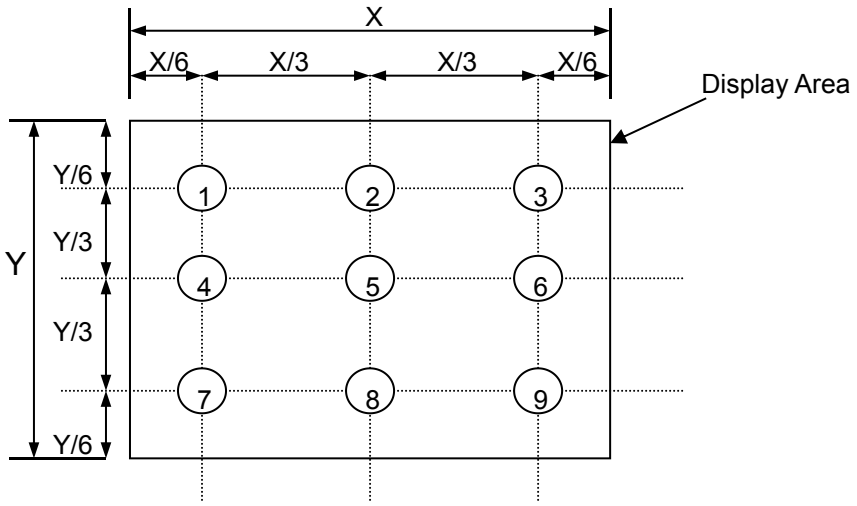
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: L_V = average (L_{P1}:L_{P9})

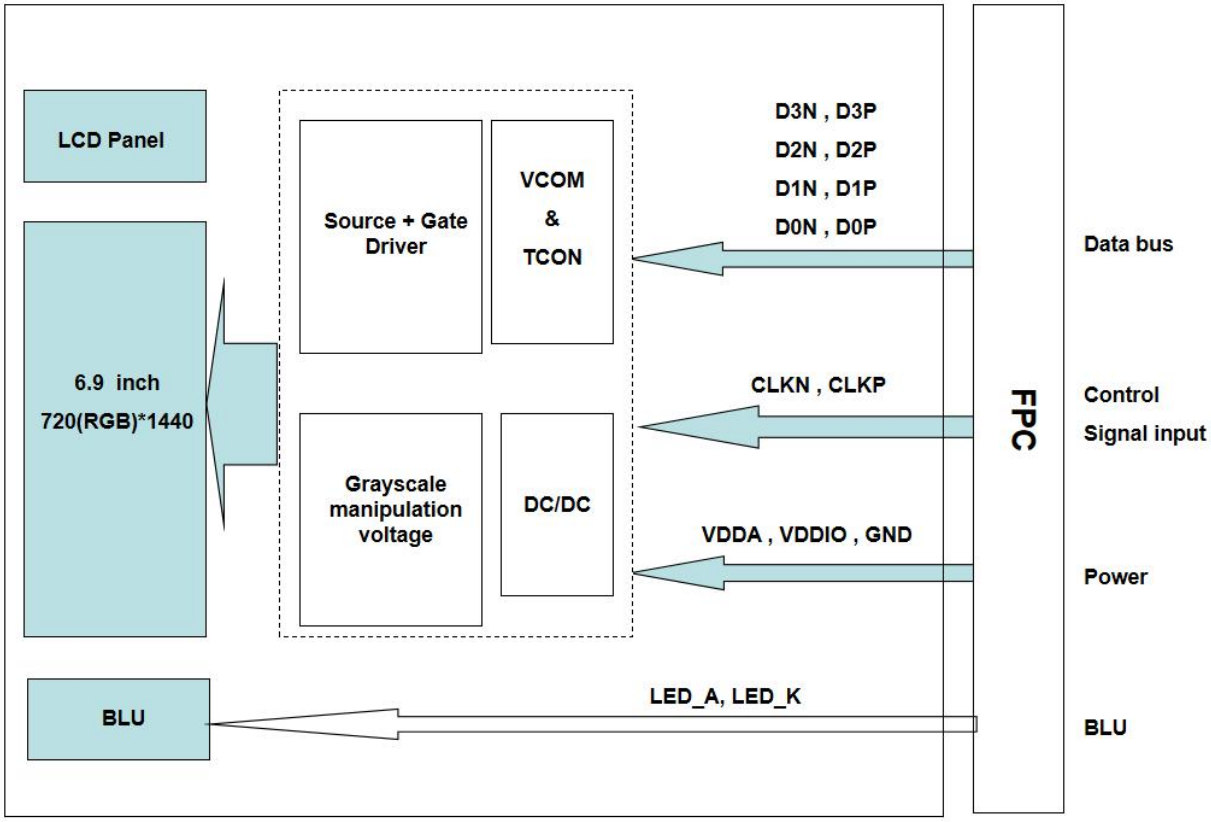
6.6.2. Uniformity = Minimal (L_{P1}:L_{P9}) / Maximal (L_{P1}:L_{P9}) * 100%

6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



8. Interface Pins Definition

No.	Symbol	Function	Remark
1	LED_A	Led anode	
2	LED_K	Led cathode	
3	VDDA	A power supply for analog circuit	
4	VDDIO	A power supply for the logic power and I/O circuit	
5	GND	Ground	
6	D0N	MIPI data Input	
7	D0P	MIPI data Input	
8	GND	Ground	
9	D1N	MIPI data Input	
10	D1P	MIPI data Input	
11	GND	Ground	
12	CLKN	MIPI clock Input	
13	CLKP	MIPI clock Input	
14	GND	Ground	
15	D2N	MIPI data Input	
16	D2P	MIPI data Input	
17	GND	Ground	
18	D3N	MIPI data Input	
19	D3P	MIPI data Input	
20	GND	Ground	

9. AC Characteristics

9.1. DSI Timing Characteristics

9.1.1. High Speed Mode – Clock Channel Timing

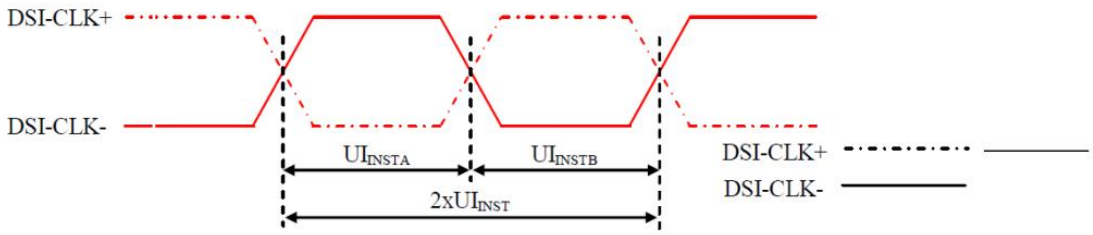


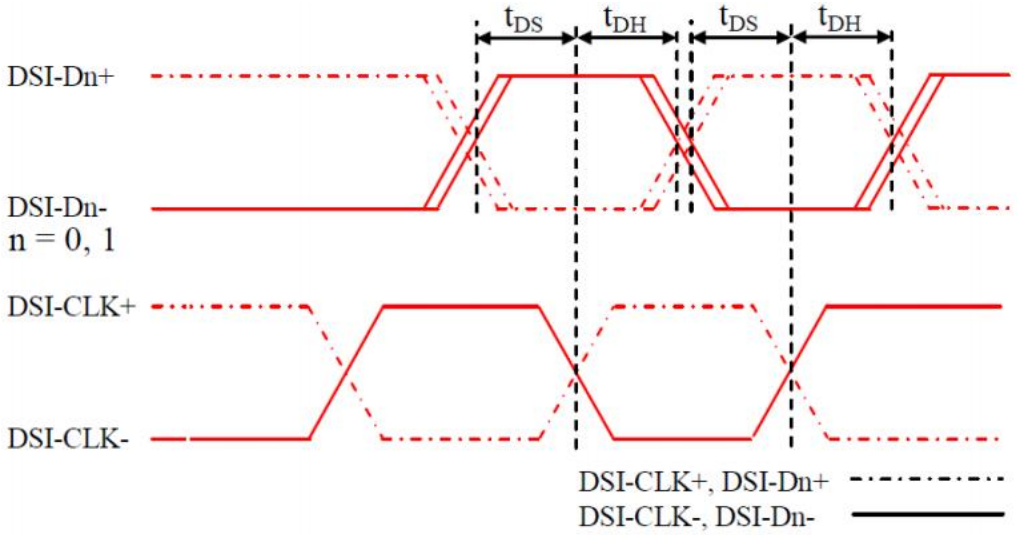
Figure 114 DSI Clock Channel Timing

Table 45 DSI Clock Channel Timing

Signal	Symbol	Parameter	Min	Max	Unit
DSI-CLK+/-	$2xUI_{INST}$	Double UI instantaneous	4	25	ns
DSI-CLK+/-	UI_{INSTA},UI_{INSTB}	UI instantaneous Half	2	12.5	ns

Note: $UI = UI_{INSTA} = UI_{INSTB}$

9.1.2. High Speed Mode – Data Clock Channel Timing

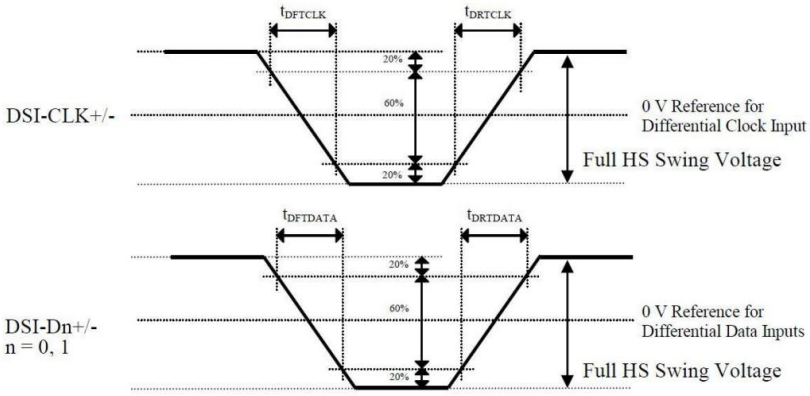


DSI Data to Clock Channel Timings

Signal	Symbol	Parameter	Min	Max
DSI-Dn+/- , n=0 and 1	t_{DS}	Data to Clock Setup time	0.15xUI	-
	t_{DH}	Clock to Data Hold Time	0.15xUI	-

DSI Data to Clock Channel Timings

9.1.3. High Speed Mode – Rise and Fall Timings



Rise and Fall Timings on Clock and Data Channels

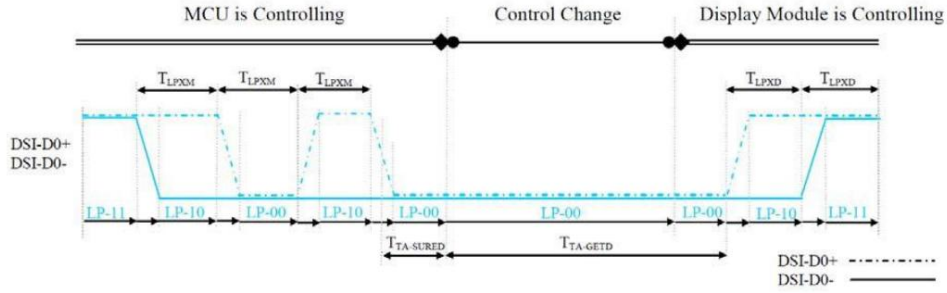
Parameter	Symbol	Condition	Specification			Unit
			Min	Typ	Max	
Differential Rise Time for Clock	t_{DRTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Rise Time for Data	$t_{DRTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps
Differential Fall Time for Clock	t_{DFTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Fall Time for Data	$t_{DFTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps

Note:The display module has to meet timing requirements, what are defined for the transmitter (MPU) on MIPI D-Phy standard

9.1.4. Low Speed Mode – Bus Turn Around

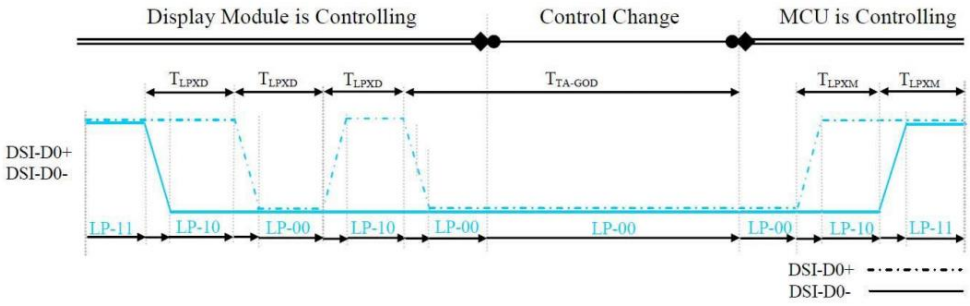
BTA from the MPU to the Display Module

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the MPU to the Display Module (GC9702P) sequence below.



BTA from the Display Module to the MPU

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the Display Module (GC9702P) to the MPU sequence below.



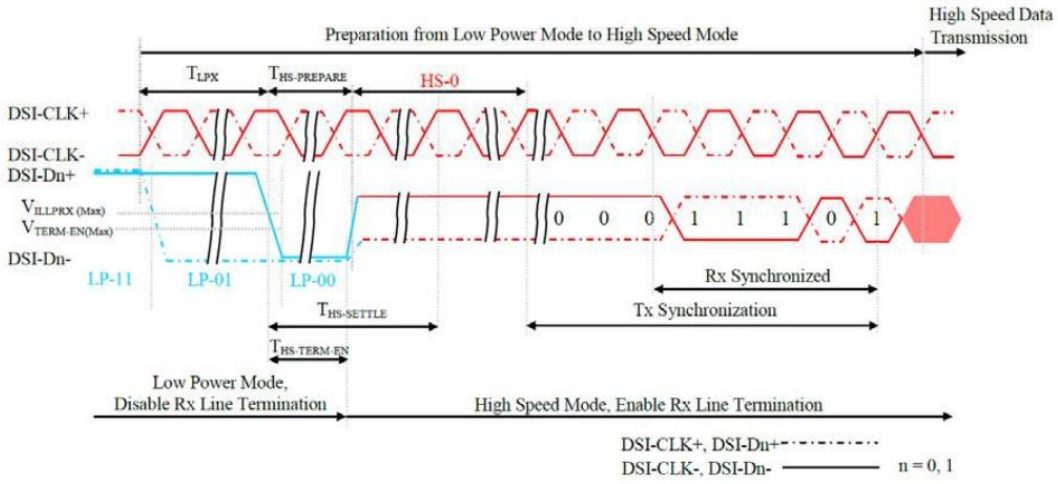
Low Power State Period Timings – A

Signal	Symbol	Description	Min	Max	Unit
DSI-D0+/-	T_{LPXM}	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU ⇑ Display Module (GC9702P)	50	75	ns
DSI-D0+/-	T_{LPXD}	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module (GC9702P) ⇑ MPU	50	75	ns
DSI-D0+/-	$T_{TA-SURED}$	Time-out before the Display Module (GC9702P) starts driving	T_{LPXD}	$2\times T_{LPXD}$	ns

Low Power State Period Timings – B

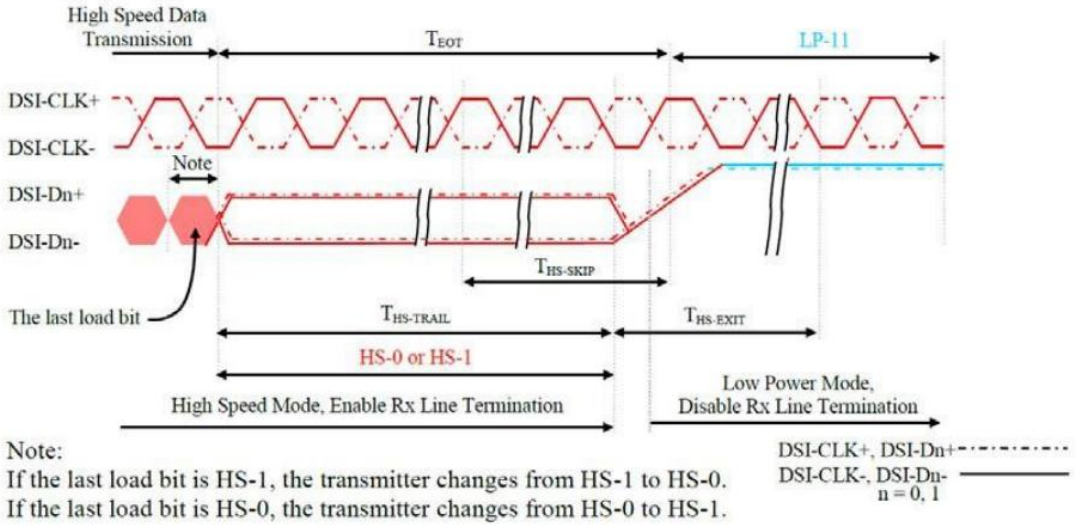
Signal	Symbol	Description	Time	Unit
DSI-D0+/-	$T_{TA-GETD}$	Time to drive LP-00 by Display Module (GC9702P)	$5\times T_{LPXD}$	ns
DSI-D0+/-	T_{TA-GOD}	Time to drive LP-00 after turnaround request – MPU	$4\times T_{LPXD}$	ns

9.1.5. Data Lanes from Low Power Mode to High Speed Mode



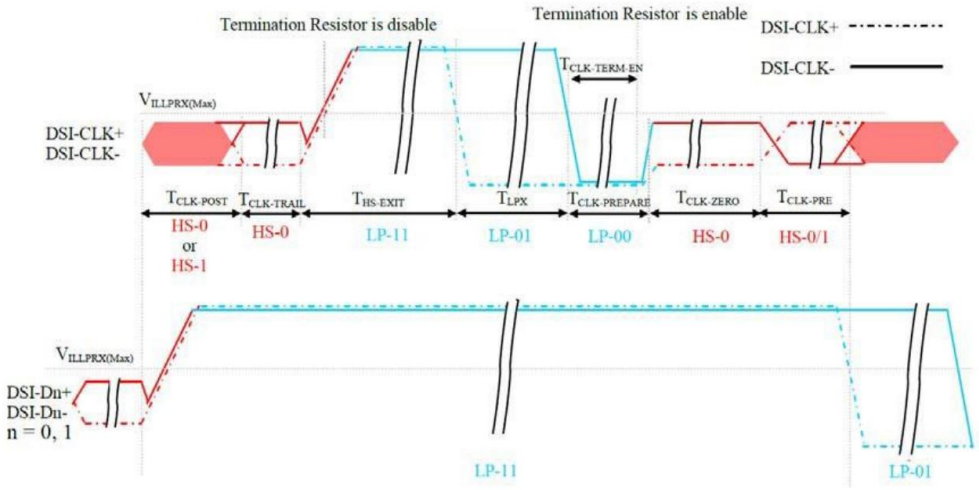
Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	T_{LPX}	Length of any Low Power State Period	50	-	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS Transmission	40+4xUI	85+6xUI	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-TERM-EN}$	Time to enable Data Lane Receiver line termination measured from when Dn crosses VILMAX	-	35+4xUI	ns

9.1.6. Data Lanes from High Speed Mode to Low Power Mode



Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	$T_{HS-SKIP}$	Time-Out at Display Module (GC9702P) to ignore transition period of EoT	40	55+4xUI	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-EXIT}$	Time to driver LP-11 after HS burst	100	-	ns

9.2. DSI Clock Burst – High Speed Mode to/from Low Power Mode



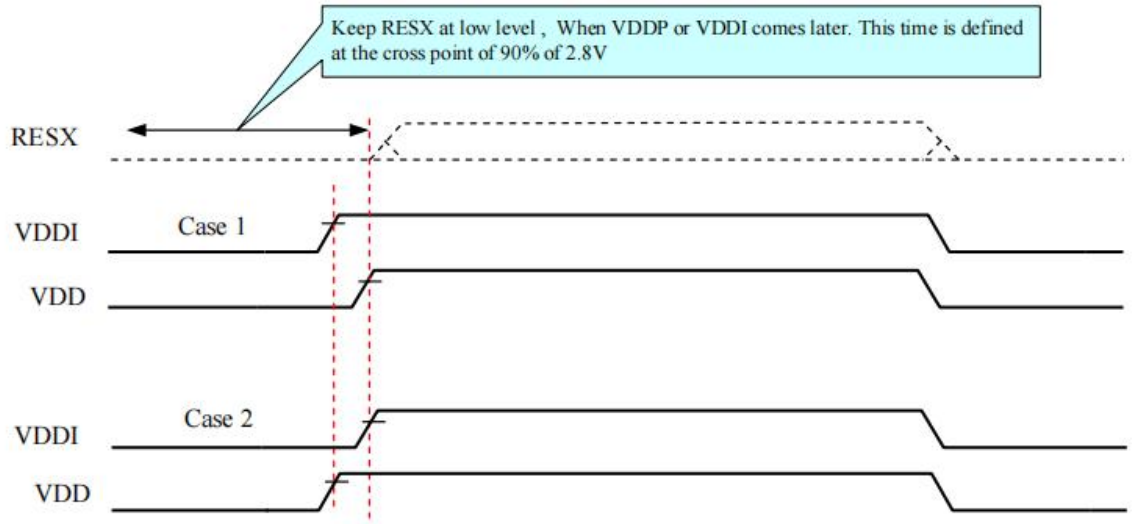
Signal	Symbol	Description	Min	Max	Unit
DSI-CLK+/-	$T_{CLK-POST}$	Time that the MPU shall continue sending HS clock after the last associated Data Lanes has transitioned to LP mode	60+52xUI	-	ns
DSI-CLK+/-	$T_{CLK-TRAIL}$	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns
DSI-CLK+/-	$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	38	95	ns
DSI-CLK+/-	$T_{CLK-TERM-EN}$	Time-out at Clock Lane to enable HS termination	-	38	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Minimum lead HS-0 drive period before starting Clock	300	-	ns
DSI-CLK+/-	$T_{CLK-PRE}$	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	8xUI	-	ns

9.3. Power ON/OFF Sequence

VDDI and VDD can be applied (or powered down) in any order. During the power off sequences, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down with minimum 120msec, and if LCD is in the Sleep In mode, VDD and VDDI can be powered down with minimum 0msec after RESX has been released.

Note:

1. There will be no damage to GC9702P if the power sequences are not met.
2. There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.
3. There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out command. Also between receiving Sleep In command and Power Off Sequence.
4. If RESX line is not held stable by host during Power On Sequence as defined in Sections 7.1 and 7.2, then it will be necessary to apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is not guaranteed.



10. Quality Assurance

10.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

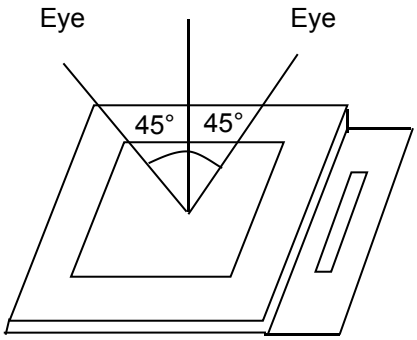
10.5. Standard of the Product Visual Inspection

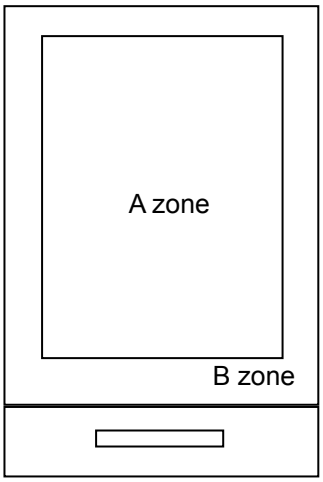
10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



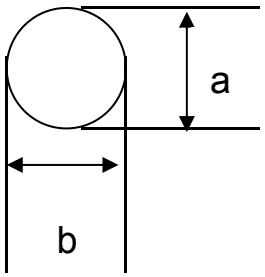


10.5.2. Basic principle:

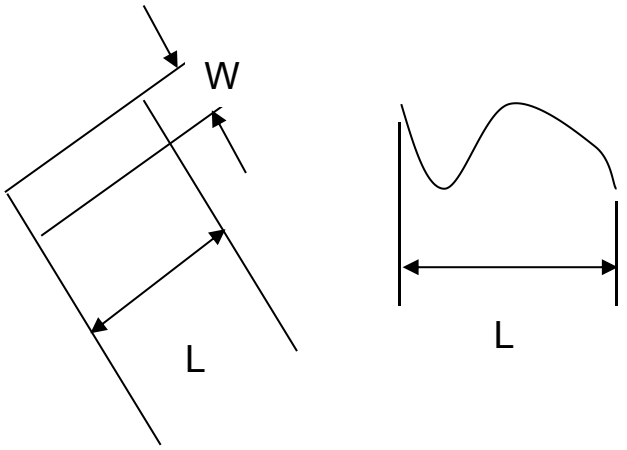
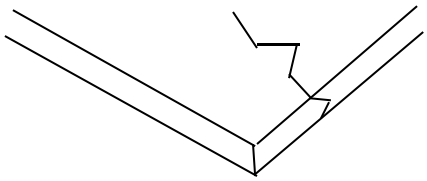
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

10.5.2.2. New item must be added on time when it is necessary.

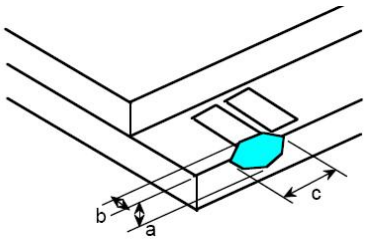
10.6. Inspection Specification

<table>
<tr><th>No.</th><th>Item</th><th>Criteria (Unit: mm)</th></tr>
<tr><td>01</td><td>Black / White spot
Foreign material
(Round type)
Pinholes
Stain
Particles inside cell.
(Minor defect)</td><td>


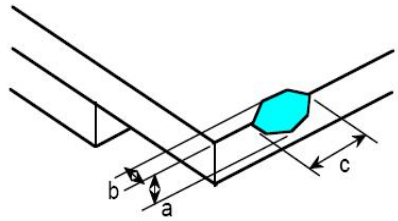
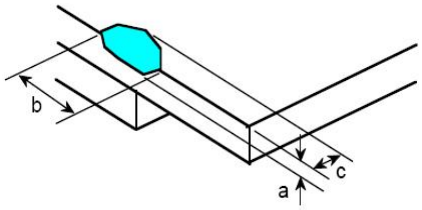
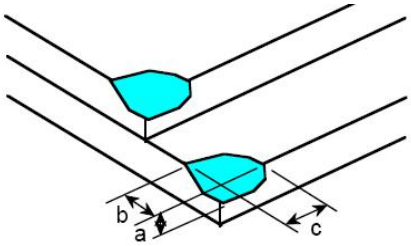
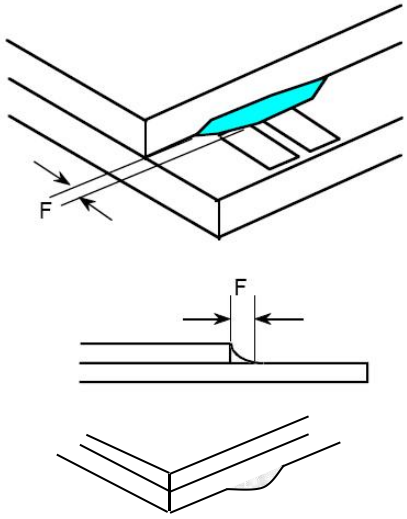
<table>
<tr><th>Area / Size</th><th>Acc. Qty</th></tr>
<tr><td>φ≤0.20</td><td>Ignore</td></tr>
<tr><td>0.20<φ≤0.50</td><td>N≤3</td></tr>
<tr><td>0.50<φ</td><td>0</td></tr>
</table>
φ= (a + b) /2
Distance between 2 defects should more than 3mm apart.
</td></tr>
<tr><td>02</td><td>Electrical Defect
(Minor defect)</td><td>
<table>
<tr><td></td><td>Display Area</td><td>Total</td><td rowspan="4">Note1</td></tr>
<tr><td>Bright dot</td><td>N⩽2</td><td>N⩽2</td></tr>
<tr><td>Dark dot</td><td>N⩽4</td><td>N⩽4</td></tr>
<tr><td>Total dot</td><td>N⩽4</td><td>N⩽4</td></tr>
<tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td>Note 2</td></tr>
</table>
Remark:
1. Bright dot caused by scratch and foreign object accords to item 1.
</td></tr>
</table>

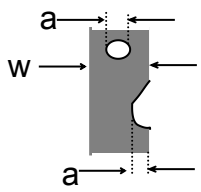
03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.

Length	Width	Acc. Qty
/	W ≦ 0.03	Ignore
L ≦ 2.5	0.03 ＜ W ≦ 0.05	3
L ≦ 2.5	0.05 ＜ W ≦ 0.10	2
/	0.1 ＜ W	0
Total		3

05	Glass Chipping Pad Area: (Minor defect) 	

Length and Width	Acc. Qty
c > 3.0, b< 1.0	1
c< 3.0, b< 1.0	3
a<Glass Thickness	

<table>
<tr>
<td>06</td>
<td>Glass Chipping Rear of Pad Area:
(Minor defect)
 
</td>
<td><table>
<tr><th>Length and Width</th><th>Acc. Qty</th></tr>
<tr><td>c > 3.0, b< 1.0</td><td>1</td></tr>
<tr><td>c< 3.0, b< 1.0</td><td>2</td></tr>
<tr><td>c< 3.0, b< 0.5</td><td>4</td></tr>
<tr><td colspan="2">a<Glass Thickness</td></tr>
</table></td>
</tr>
<tr>
<td>07</td>
<td>Glass Chipping Except Pad Area:
(Minor defect)
 
</td>
<td><table>
<tr><th>Length and Width</th><th>Acc. Qty</th></tr>
<tr><td>c > 3.0, b< 1.0</td><td>1</td></tr>
<tr><td>c< 3.0, b< 1.0</td><td>2</td></tr>
<tr><td>c< 3.0, b< 0.5</td><td>4</td></tr>
<tr><td colspan="2">a<Glass Thickness</td></tr>
</table></td>
</tr>
<tr>
<td>08</td>
<td>Glass Corner Chipping:
(Minor defect)
 
</td>
<td><table>
<tr><th>Length and Width</th><th>Acc. Qty</th></tr>
<tr><td>c < 3.0, b< 3.0</td><td>Ignore</td></tr>
<tr><td colspan="2">a<Glass Thickness</td></tr>
</table></td>
</tr>
<tr>
<td>09</td>
<td>Glass Burr:
(Minor defect)
 
</td>
<td><table>
<tr><th>Length</th><th>Acc. Qty</th></tr>
<tr><td>F < 1.0</td><td>Ignore</td></tr>
</table>
Glass burr don’t affect assemble and module dimension.</td>
</tr>
</table>

<table>
<tr><td>10</td><td>FPC Defect:
(Minor defect)
 
</td><td>10.1 Dent, pinhole width a<w/3.
(w: circuitry width.)
10.2 Open circuit is unacceptable.
10.3 No oxidation, contamination and distortion.</td></tr>
<tr><td>11</td><td>Bubble on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>12</td><td>Dent on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>13</td><td>Bezel</td><td>13.1 No rust, distortion on the Bezel.
13.2 No visible fingerprints, stains or other contamination.</td></tr>
<tr><td>14</td><td>PCB</td><td>14.1 No distortion or contamination on PCB terminals.
14.2 All components on PCB must same as documented on the BOM/component layout.
14.3 Follow IPC-A-600F.</td></tr>
<tr><td>15</td><td>Soldering</td><td>Follow IPC-A-610C standard</td></tr>
<tr><td>16</td><td>Electrical Defect
(Major defect)</td><td>The below defects must be rejected.
16.1 Missing vertical / horizontal segment,
16.2 Abnormal Display.
16.3 No function or no display.
16.4 Current exceeds product specifications.
16.5 LCD viewing angle defect.
16.6 No Backlight.
16.7 Dark Backlight.
16.8 Touch Panel no function.</td></tr>
</table>

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

10.7.2. Two minor defects are equal to one major in lot sampling inspection.

10.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

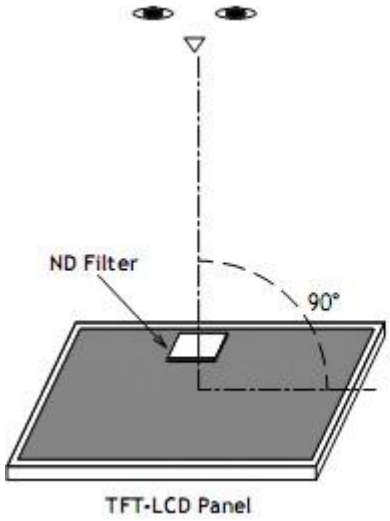
10.9. Packing

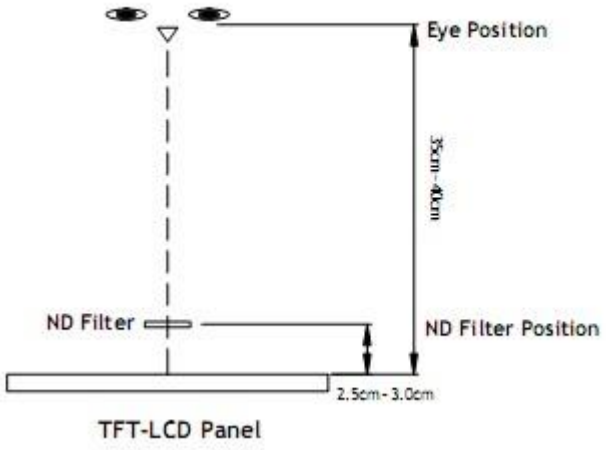
10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

10.9.2. Modules inside package box should have compliant mark.

10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.





Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	**70℃, 96Hrs**	2	GB/T2423.2 -2008
2	Low Temperature Operating	**-20℃, 96Hrs**	2	GB/T2423.1 -2008
3	High Humidity Storage	**50℃, 90%RH, 96Hrs**	2	GB/T2423.3 -2016
4	High Temperature Storage	**80℃, 96Hrs**	2	GB/T2423.2 -2008
5	Low Temperature Storage	**-30℃, 96Hrs**	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	**-20℃, 60min ~ 70℃, 60min, 20 cycles.**	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air:±4KV 150pF/330Ω 5 times Contact:±2KV 150pF/330Ω 5 times	2	GB/T17626.2 -2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1. Safety

12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.

12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3. Storage

12.3.1. Do not store the LCD module beyond the specified temperature ranges.

12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

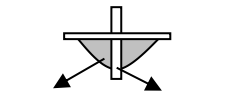
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

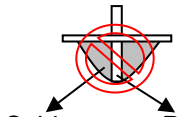
Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



Recommended



Not Recommended

12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270～290℃

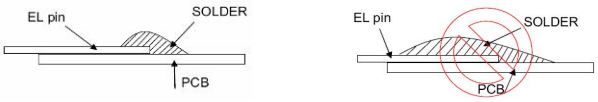
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting

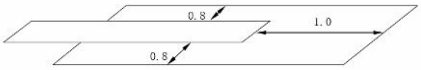


Recommended Not Recommended

12.4.2.7. The type of the solder iron:

Recommended Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

12.5.1. Do not drive LCD with DC voltage

12.5.2. Response time will increase below lower temperature

12.5.3. Display may change color with different temperature

12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.

12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.

12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.

12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.

12.5.8. Do not display the fixed pattern for long time（we suggest the time not longer than one hour）because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.

12.6.2. The normal static prevention measures should be observed for work clothes and benches.

12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

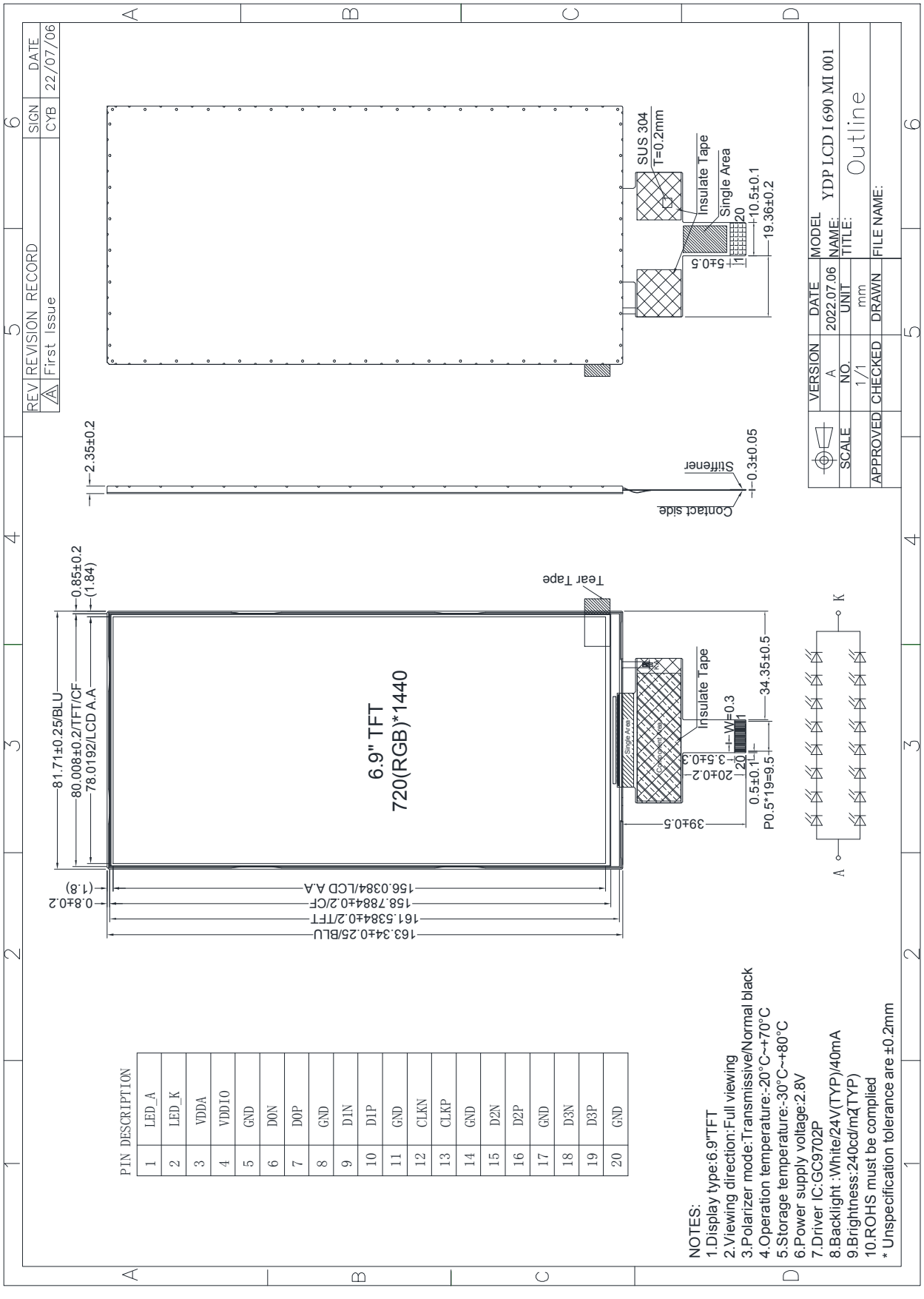
12.7. Limited Warranty

12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.

12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.

12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD

14. Outline Drawing